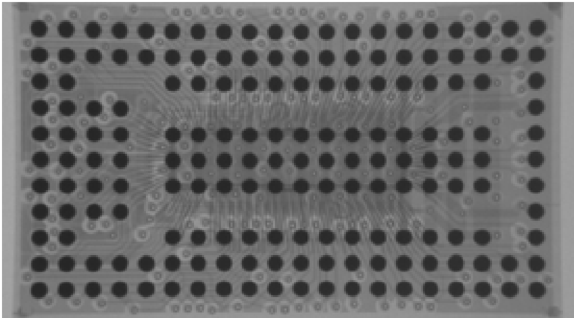
eurofins | EAG Laboratories

PICTURE BOOK

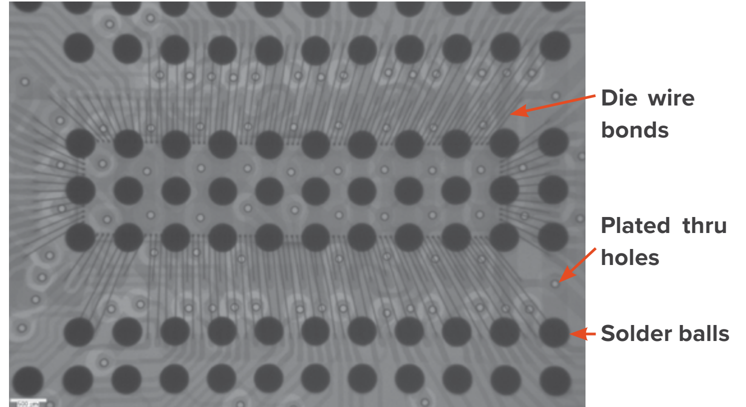
Package Delayering Services at EAG

PCB or Package samples can be delayered and examined at each layer. This is helpful in looking for opens, shorts, leakage and damage in the layers as well as design rule distances with in such samples. Packages can also be removed to allow analysis from the backside of die.

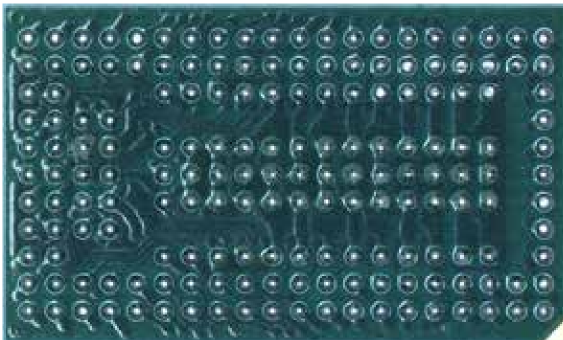
LOW MAG X-RAY TOP VIEW OF PACKAGE



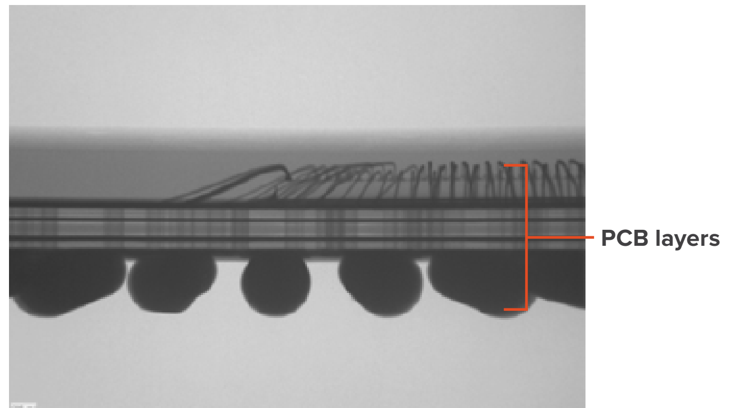
ZOOM-IN X-RAY TOP VIEW



SOLDER BALL SIDE OF DEVICE

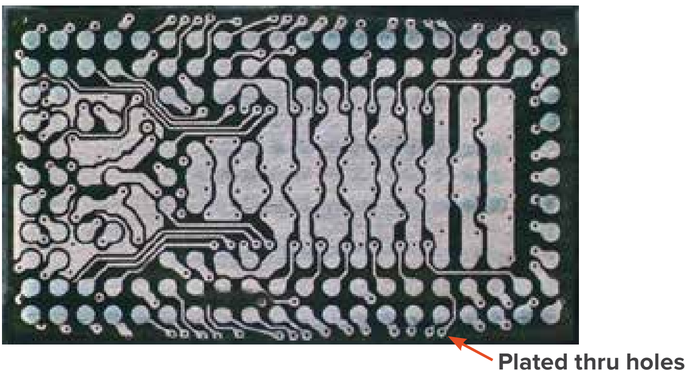


SIDE VIEW X-RAY



The device is then polished away layer by layer so that examination, images and analysis can be performed as needed.

VIEW OF LAYER 4 TRACES



VIEW OF LAYER 4 TO LAYER 3 PLATED THRU HOLE VIAS

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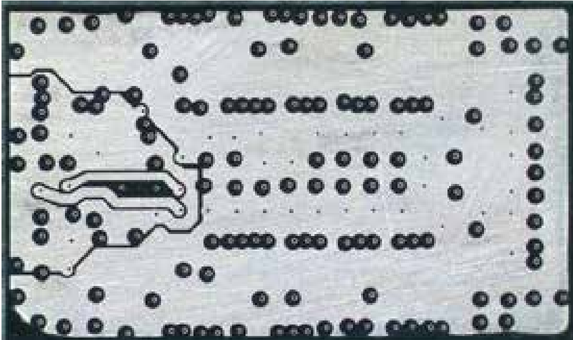
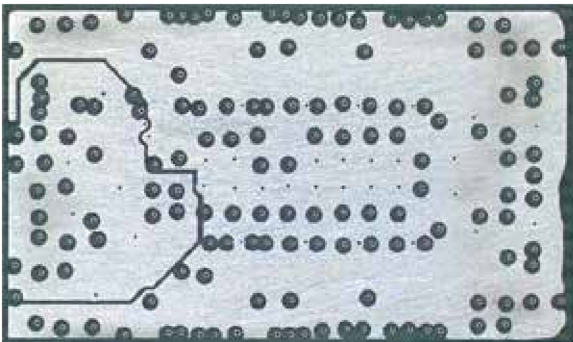
Package Delayering Services at EAG

VIEW OF LAYER 3 TRACES

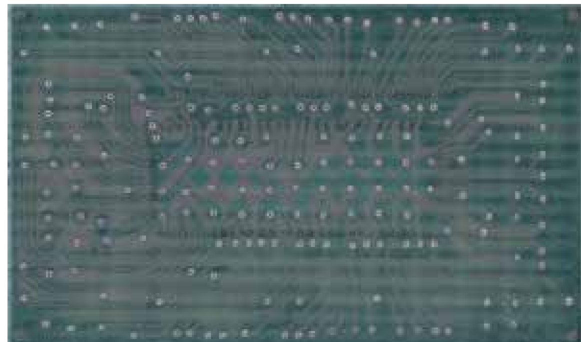


VIEW OF LAYER 3 TO LAYER 2 PLATED THRU HOLE VIAS

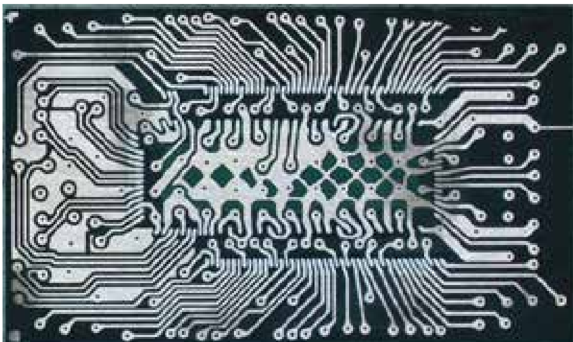
VIEW OF LAYER 2 TRACES



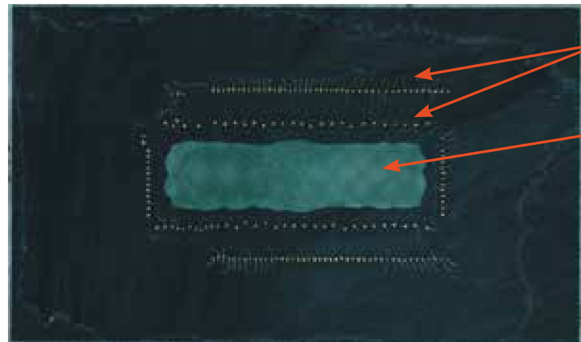
VIEW OF LAYER 2 TO LAYER 1 PLATED THRU HOLE VIAS



VIEW OF LAYER 1 TRACES



VIEW OF STITCH BONDS THAT GO TO THE TOP OF THE DIE SURFACE



The exposure of the die and the wire bonds allows Emission/OBIRCH/IR techniques to be applied to the device.

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